BGA Heat Sink - High Performance Device Specific - NXP





ATS Part#:

ATS-59002-C1-R0

Description: 25

25.00 x 32.00 x 13.00 mm BGA Heat Sink - High Performance Device Specific - NXP

 Heat Sink Type:
 NXP

 Heat Sink Attachment:
 maxiGRIP

 Equivalent Part Number:
 ATS-59002-C2-R0 Discontinued

*Image above is for illustration purpose only.

Features & Benefits

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- · Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	6.5 °C/W	5 °C/W	4.1 °C/W	3.6 °C/W	3.2 °C/W	3 °C/W	2.7 °C/W
	Ducted Flow	3.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	25.00 mm	32.00 mm	13.00 mm	46.5 mm	T766	BLACK-ANODIZED
*Image above is for illustration purpose only.	 Dimension ATS-5900 (Saint Go Thermal p application ATS resen performar ATS certifi Optional r 	rves the right to upd	tion/Removal Tool S	ly with an equivalent 00F is discontinued ence only. Actual per oducts without notice S-6 and REACH cor Set P/N: MGT170	t thermal effective rformance	interface material 12/31/10. e may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), **sales@qats.com** or **www.qats.com**.



© 2013 Advanced Thermal Solutions, Inc. | 89-27 Access Road | Norwood MA | 02062 | USA